

ESD224 HDMIインターフェイス用の低クランピング、4チャンネルのESD保護デバイス

1 特長

- IEC 61000-4-2 レベル4 ESD保護
 - 接触放電 $\pm 12\text{kV}$
 - エアギャップ放電 $\pm 15\text{kV}$
- IEC 61000-4-4 EFT保護
 - 80A (5/50ns)
- IEC 61000-4-5 サージ保護
 - 2A (8/20 μs)
- IO容量
 - 0.5pF (標準値)
- HDMI 2.0準拠**
- 非常に低いリーク電流: 0.1nA (標準値)
- 非常に低いESDクランピング電圧: 16A TLPにおいて8V (システム側)
- 最大6Gbpsの高速インターフェイスをサポート
- 工業用温度範囲: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$
- 業界標準のDQAパッケージ

2 アプリケーション

- 最終製品
 - セットトップ・ボックス
 - TVおよびモニタ
 - ラップトップおよびデスクトップPC
 - DVD、Blu-ray、マルチメディア・プレイヤー
- インターフェイス
 - HDMI 2.0/1.4
 - イーサネット10/100/1000Mbps
 - USB 3.0

3 概要

ESD224は、USB 3.0およびHDMI 2.0などの高速アプリケーション用の双方向TVS ESD保護ダイオード・アレイです。ESD224は、IEC 61000-4-2国際規格で規定されている最大レベル(レベル4)のESD耐性を備えています。ESD224は、差動マッチングされた直列素子を内蔵することで、下流のESDクランピング性能を拡張するとともに、高速インターフェイスへの信号の準拠を維持しています。ESD224の内蔵ESD保護回路で実現される非常に低いクランピング性能と高い差動帯域幅により、このデバイスはHDMI 2.0に準拠しながら、下流のHDMIデバイスを堅牢に保護できます。

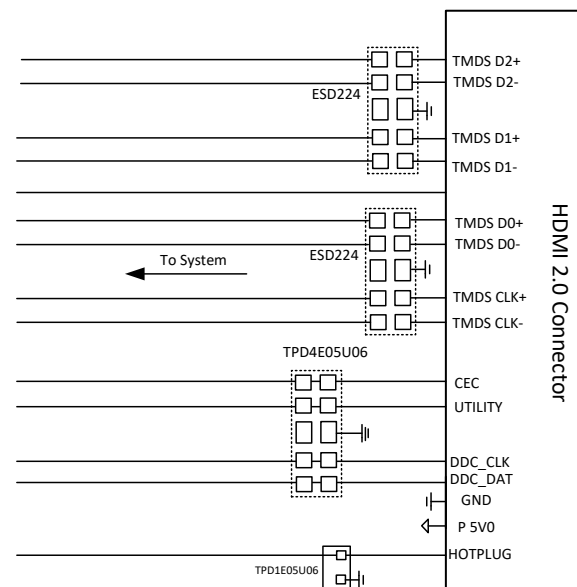
ESD224は、業界標準のUSON-10 (DQA)パッケージで供給されます。このパッケージは0.5mmピン・ピッチを採用しているため、実装が容易で、設計時間を短縮できます。

製品情報⁽¹⁾

型番	パッケージ	本体サイズ(公称)
ESD224	USON (10)	2.50mm×1.00mm

(1) 提供されているすべてのパッケージについては、データシートの末尾にある注文情報を参照してください。

代表的なアプリケーションの回路図



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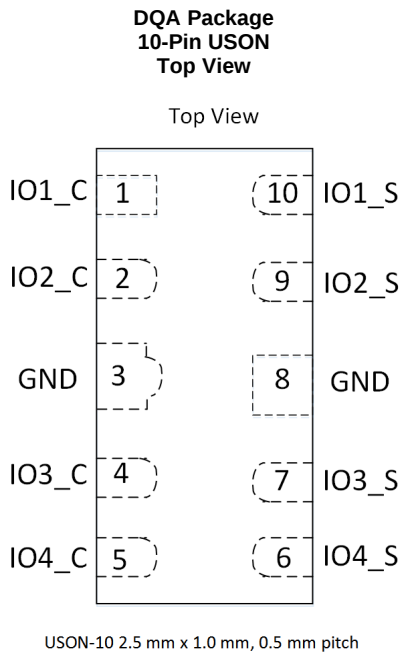
4 改訂履歴

2018年2月発行のものから更新

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•	製品のステータスを「事前情報」から「量産データ」に変更	1
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5 Pin Configuration and Functions



Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
GND	3	Ground	Ground. Connect to ground. These pins are shorted internally.
GND	8		
IO1_C	1	Connector Side I/O	ESD protected channel to be connected to the connector
IO2_C	2		
IO3_C	4		
IO4_C	5		
IO4_S	6	System Side I/O Pin corresponding to IO4_C	To be connected to the system side
IO3_S	7	System Side I/O Pin corresponding to IO3_C	
IO2_S	9	System Side I/O Pin corresponding to IO2_C	
IO1_S	10	System Side I/O Pin corresponding to IO1_C	

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Electrical Fast Transient	IEC 61000-4-4 Peak Current at 25°C		80	A
Peak Pulse	IEC 61000-4-5 Surge (t_p 8/20 μ s) Peak Power at 25°C		17	W
	IEC 61000-4-5 Surge (t_p 8/20 μ s) Peak Current at 25°C		2	A
T_A	Operating free-air temperature	-40	125	°C
T_{stg}	Storage temperature	-65	155	°C

- (1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings -JEDEC Specifications

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±2500	V
	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 ESD Ratings - IEC Specifications

		VALUE	UNIT
$V_{(ESD)}$ Electrostatic discharge	IEC 61000-4-2 Contact Discharge, all pins	±12000	V
	IEC 61000-4-2 Air Discharge, all pins	±15000	

6.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_{IN}	Input voltage	-3.6		3.6	V
T_A	Operating Free Air Temperature	-40		125	°C

6.5 Thermal Information

THERMAL METRIC ⁽¹⁾		ESD224	UNIT
		DQA (USON)	
		10 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	173.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	109.6	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	77.6	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	14.3	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	77.3	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.6 Electrical Characteristics

At $T_A = 25^\circ\text{C}$ unless otherwise noted

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{RWM}	Reverse stand-off voltage	$I_{IO} < 10 \text{ nA}$, across operating temperature range	-3.6		3.6	V
V_{BRF}	Breakdown voltage, Pin 1, 2, 4, 5 to 3 (GND) ⁽¹⁾	$I_{IO} = 1 \text{ mA}$	5		7.9	V
V_{BRR}	Reverse breakdown voltage, pin 1, 2, 4, 5 to 3 (GND) ⁽¹⁾	$I_{IO} = -1 \text{ mA}$	-7.9		-5	V
V_{HOLD}	Holding voltage, pin1, 2, 4, 5 to 3 (GND) and 3 (GND) to pin 1, 2, 4, 5 ⁽²⁾	$I_{IO} = 1 \text{ mA}$		6.3		V
$V_{HOLD-NEG}$	Breakdown voltage, pin1, 2, 4, 5 to 3 (GND) ⁽²⁾	$I_{IO} = -1 \text{ mA}$		-6.3		V
V_{CLAMP}	TLP Clamping voltage (Intrinsic)	IPP = 1 A, pin 1, 2, 4, 5 to 3 or 8(GND), GND to pin 1, 2, 4, 5		7		V
		IPP = 5 A, pin 1, 2, 4, 5 to 3 or 8(GND), GND to pin 1, 2, 4, 5		9		V
		IPP = 16 A, pin 1, 2, 4, 5 to 3 or 8(GND), GND to pin 1, 2, 4, 5		14		V
$V_{CLAMP-IEC-SYS}$	IEC 61000-4-2 30 ns Clamping voltage (system side) assuming system draws at least 3 A of current at 8 V. See measurement setup.	8-kV Contact discharge on pin 1, 2, 4, 5 with pin3 grounded. Voltage waveform measured at pin 6, 7, 9, 10 with respect to GND		8		V
		-8-kV Contact discharge on pin 1, 2, 4, 5 with pin3 grounded. Voltage waveform measured at pin 6, 7, 9, 10 with respect to GND		-5		V
R_{DYN}	Dynamic resistance	Pin 1, 2, 4, 5 to GND, 100 ns TLP		0.5		Ω
		GND to Pin 1, 2, 4, 5, 100 ns TLP		0.5		
C_{LINE}	Line capacitance, any IO to GND	$V_{IO} = 0 \text{ V}$, $V_{p-p} = 30 \text{ mV}$, $f = 1 \text{ MHz}$		0.5	0.6	pF
ΔC_{LINE}	Variation of line capacitance	$C_{LINE1} - C_{LINE2}$, $V_{IO} = 0 \text{ V}$, $V_{p-p} = 30 \text{ mV}$, $f = 1 \text{ MHz}$		0.02	0.07	pF
C_{CROSS}	Line-to-line capacitance between one differential pair to another differential pair	$V_{IO} = 0 \text{ V}$, $V_{rms} = 30 \text{ mV}$, $f = 1 \text{ MHz}$		0.28		pF
S_{21DC}	DC Insertion Loss	DC insertion loss at Ch1, Ch2, Ch3, Ch4		0.3		dB
$I_{leakage}$	Leakage Current	$V_{IO} = \pm 3.6 \text{ V}$, Pin 1,2,4,5 to Pin 3		0.1	10	nA

(1) V_{BRF} and V_{BRR} are defined as the voltage obtained at 1 mA when sweeping the voltage up, before the device latches into the snapback state

(2) V_{HOLD} is defined as the voltage when 1 mA is applied, after the device has successfully latched into the snapback state.

6.7 Typical Characteristics

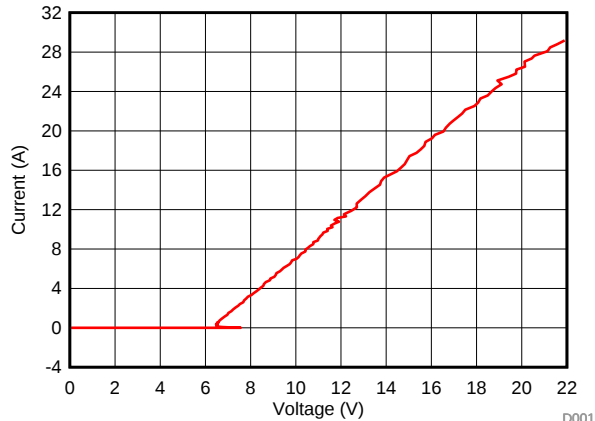


图 1. Positive TLP Curve, Connector side IO Pin to GND ($t_p=100\text{ns}$)

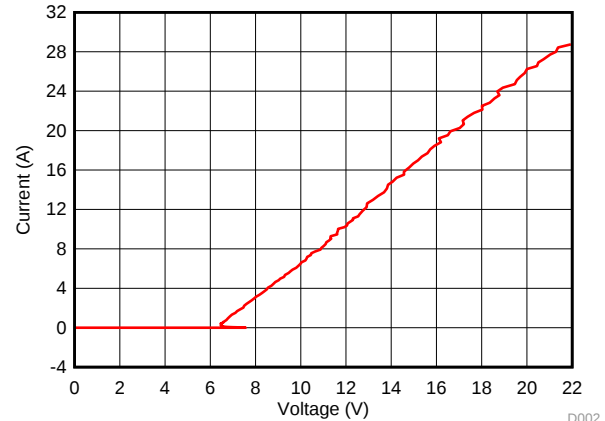


图 2. Negative TLP Curve, Connector side IO Pin to GND (Plotted as positive TLP from GND to IO, $t_p=100\text{ns}$)

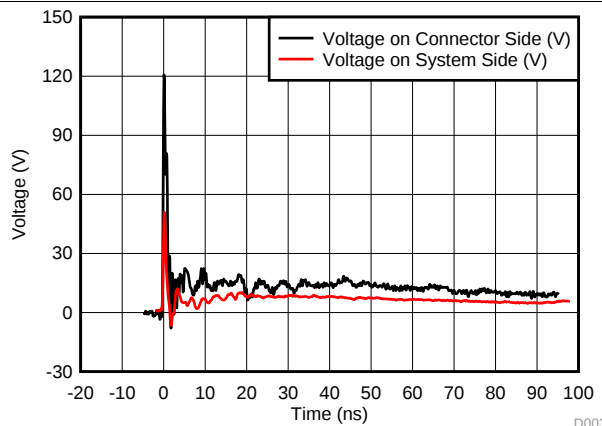


图 3. Clamping voltage waveform for +8kV IEC 61000-4-2 stress. See 图 11 for details.

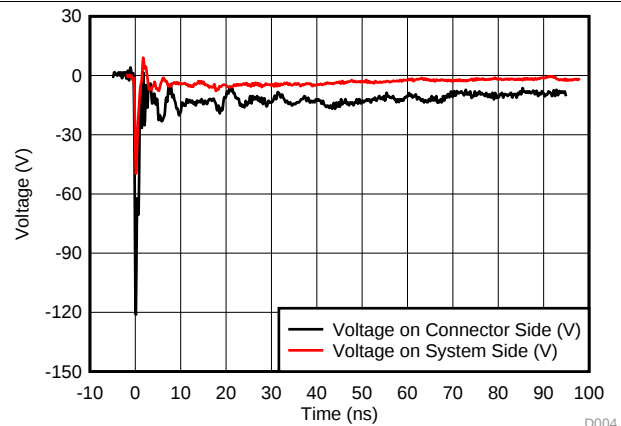


图 4. Clamping voltage waveform for -8kV IEC 61000-4-2 stress. See 图 11 for details.

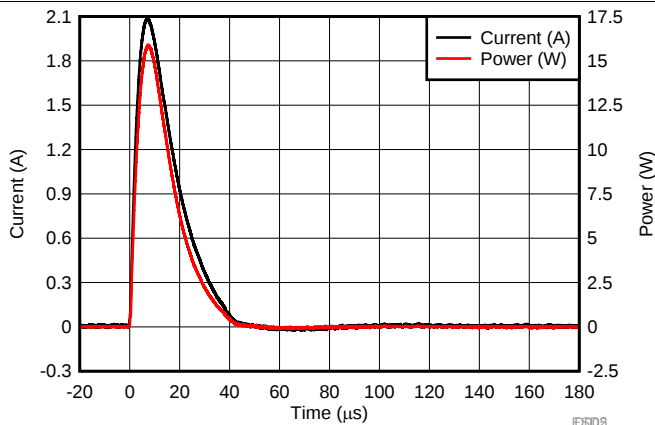


图 5. IEC 61000-4-5 Surge Waveform ($t_p=8/20\text{ }\mu\text{s}$)

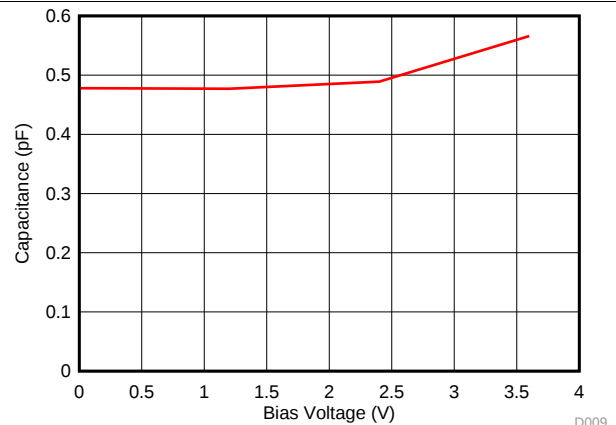


图 6. Capacitance vs. Bias Voltage at 25 degree Celsius

Typical Characteristics (continued)

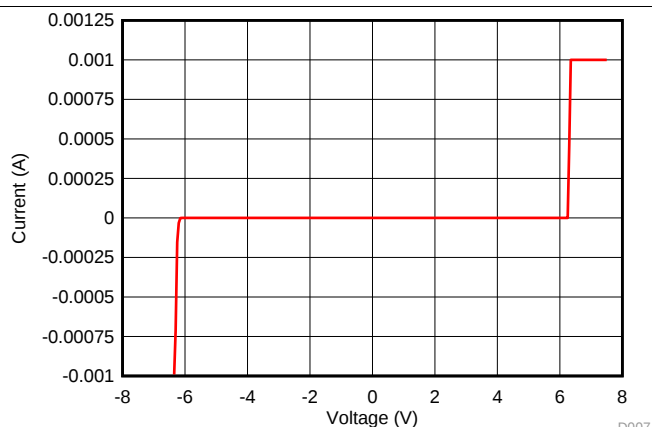


Figure 7. DC Voltage Sweep I-V Curve, IO Pin to GND

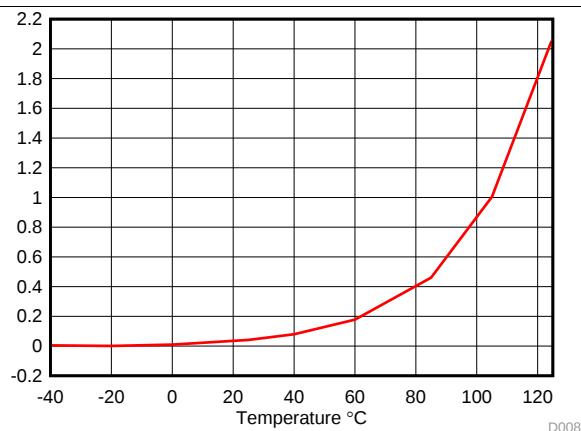


Figure 8. Leakage Current vs Temperature, IO Pin to GND, at 2.5 V Bias

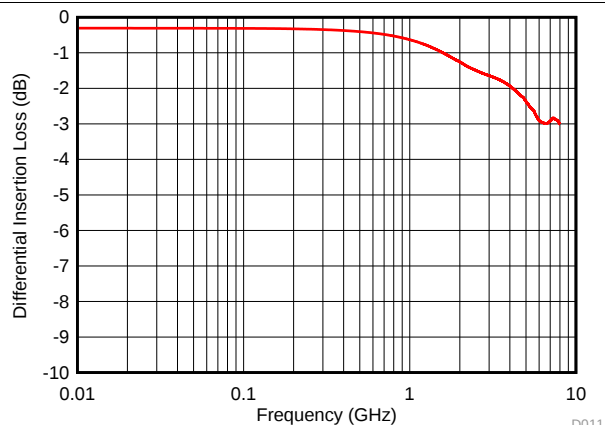


Figure 9. Differential Insertion Loss

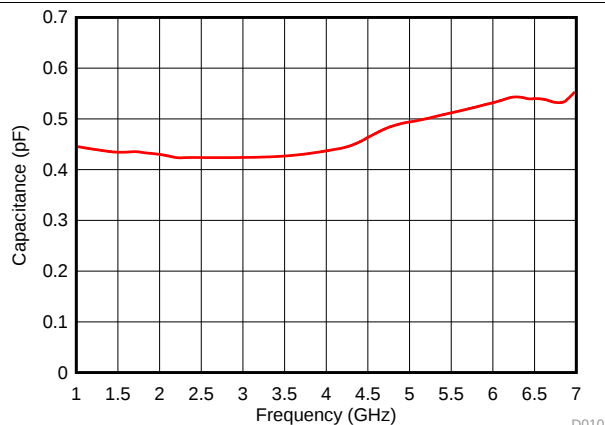
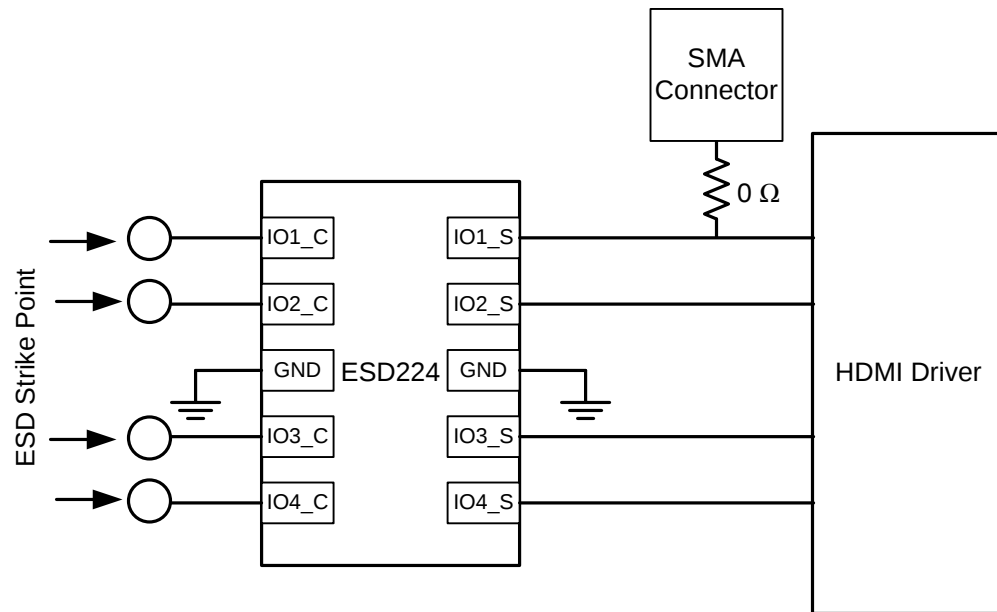


Figure 10. Capacitance vs Frequency

7 Parameter Measurement Setup

7.1 IEC 61000-4-2 System Level ESD Test Setup with HDMI Driver for Clamping Voltage Measurement

 11 shows the setup used to perform System Level ESD test to evaluate the clamping performance of ESD224 in real-world applications where the device is protecting a downstream HDMI driver System-on-Chip. IEC 61000-4-2 8kV Contact stress was applied at the connector pin and the voltage waveform on the system-side pin was captured to look at the clamping voltage presented by ESD224 to the down stream HDMI driver.



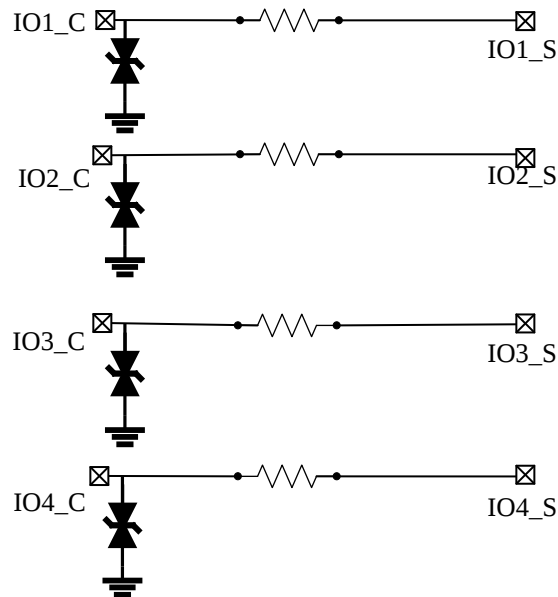
 11. System Level IEC 61000-4-2 ESD Test Setup with ESD224 protecting an HDMI driver chip

8 Detailed Description

8.1 Overview

The ESD224 is a bidirectional ESD Protection Diode with ultra-low capacitance. This device can dissipate ESD strikes above the maximum level specified by the IEC 61000-4-2 International Standard. The ultra-low capacitance makes this device ideal for protecting any super high-speed signal pins.

8.2 Functional Block Diagram



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8.3 Feature Description

8.3.1 IEC 61000-4-2 ESD Protection

The I/O pins can withstand ESD events up to ± 12 -kV contact and ± 15 -kV air gap. The ESD-surge clamp diverts the current to ground.

8.3.2 IEC 61000-4-4 EFT Protection

The I/O pins can withstand an electrical fast transient burst of up to 80 A (5/50 ns waveform, 4 kV with 50- Ω impedance). The ESD-surge clamp diverts the current to ground.

8.3.3 IEC 61000-4-5 Surge Protection

The I/O pins can withstand surge events up to 2 A and 17 W (8/20 μ s waveform). The ESD-surge clamp diverts this current to ground.

8.3.4 IO Capacitance

The capacitance between each I/O pin to ground is 0.5 pF (typical). This device supports data rates up to 6 Gbps.

8.3.5 DC Breakdown Voltage

The DC breakdown voltage of each I/O pin is a minimum of ± 5.5 V. This ensures that sensitive equipment is protected from surges above the reverse standoff voltage of ± 3.6 V.

Feature Description (continued)**8.3.6 Ultra Low Leakage Current**

The I/O pins feature an ultra-low leakage current of 10 nA (maximum) with a bias of ± 2.5 V.

8.3.7 Low ESD Clamping Voltage

The I/O pins feature an ESD clamp that is capable of clamping the voltage to 8 V ($I_{PP} = 16$ A TLP) on the system side pins when the system draws at least 3 A.

8.3.8 Supports High Speed Interfaces

This device is capable of supporting high speed interfaces up to 6 Gbps, because of the extremely low IO capacitance.

8.3.9 Industrial Temperature Range

This device features an industrial operating range of -40°C to $+125^{\circ}\text{C}$.

8.4 Device Functional Modes

The ESD224 is a passive integrated circuit that triggers when voltages are above V_{BRF} or below V_{BRR} . During ESD events, voltages as high as ± 15 kV (air) can be directed to ground via the internal diode network. When the voltages on the protected line fall below the trigger levels of ESD224 (usually within 100s of nano-seconds) the device reverts to passive.

9 Application and Implementation

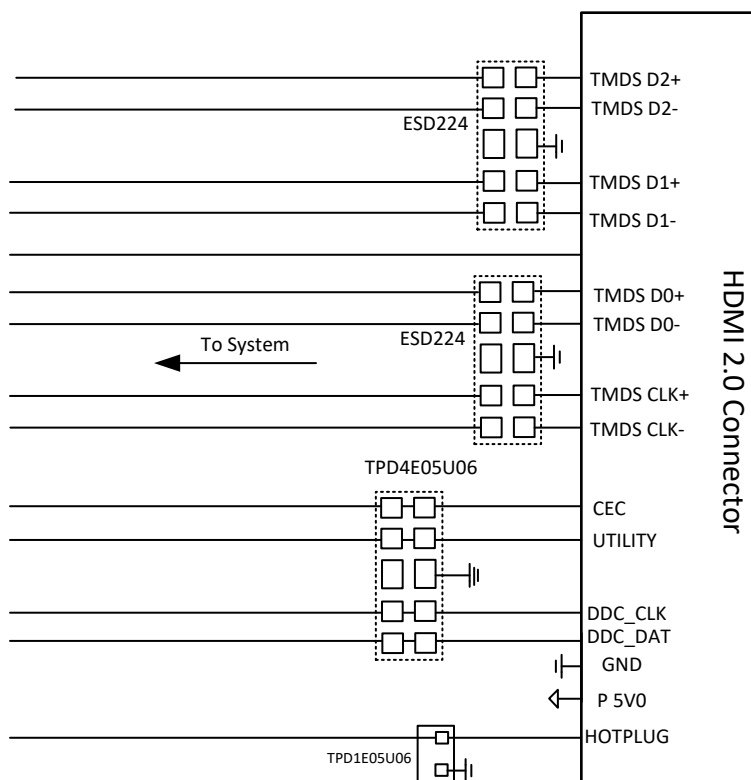
注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The ESD224 is a diode type TVS which is used to provide a path to ground for dissipating ESD events on high-speed signal lines between a human interface connector and a system. As the current from ESD passes through the TVS, only a small voltage drop is present across the diode. Part of this voltage drop across the diode drops across the series element between the connector side pin and the system-side pin. Therefore, the effective voltage drop across the protected IC is smaller than the voltage drop across the diode. It is recommended to avoid through-routing for this ESD diode (single trace connecting both the connector side pin and the system side pin) for the best ESD performance.

9.2 Typical Application



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图 12. ESD224 Protecting the HDMI Interface

Typical Application (continued)

9.2.1 Design Requirements

In this design example, two ESD224 devices, one TPD4E05U06 and one TPD1E05U06 device are used to protect an HDMI 2.0 interface. For HDMI 2.0 application design parameters listed in 表 1 are known.

表 1. Design Parameters

DESIGN PARAMETER	VALUE
Signal range on high speed differential data lines	0 to 3.6 V
Operating frequency of high speed data lines	3 GHz (First Harmonic)
Signal range on control lines (CEC, UTILITY, DDC_CLK and DDC_DAT)	0 to 5 V

9.2.2 Detailed Design Procedure

9.2.2.1 Signal Range

ESD224 supports signal ranges between -3.6 V and 3.6 V, which supports the high-speed lines on the HDMI 2.0 application. The TPD4E05U06 and TPD1E05U06 support signal ranges between 0 V and 5.5 V, which supports the HDMI control lines.

9.2.2.2 Operating Frequency

The ESD224 has a 0.5 pF (typical) capacitance, which supports the HDMI 2.0 rate of 6 Gbps. The TPD4E05U06 and TPD1E05U06 have a typical capacitance of 0.5 pF and 0.42 pF respectively, which easily support the control lines. The ESD224 has 4 identical protection channels for the differential HDMI high-speed signal lines. The symmetrical pin out of the device with a ground pin between the two differential signal pins makes it suitable for this application.

9.2.3 Application Curves

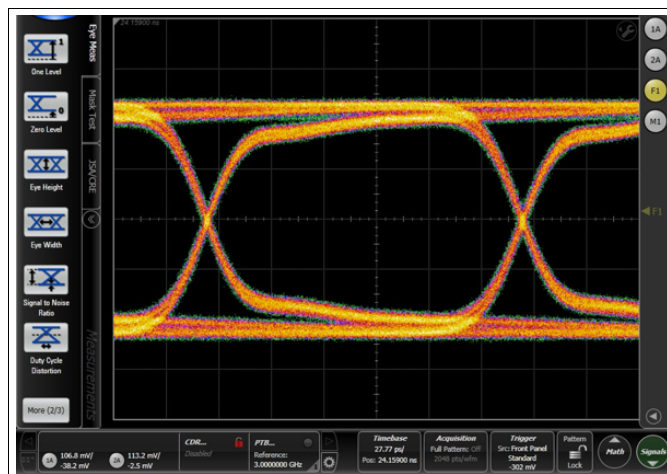


图 13. HDMI 2.0 6 Gbps Eye Diagram (Bare Board)

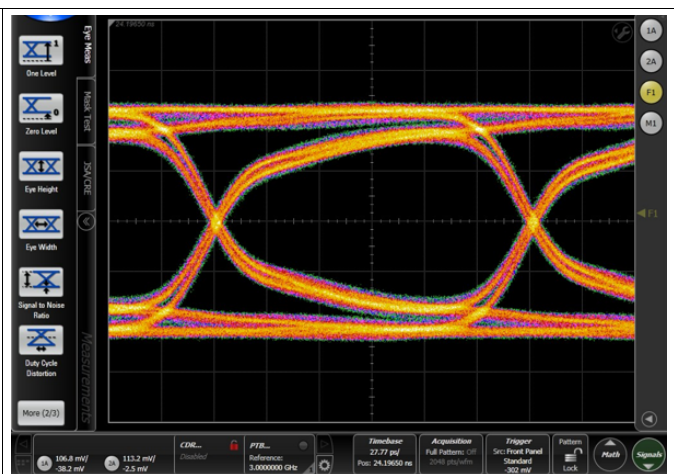


图 14. HDMI 2.0 6 Gbps Eye Diagram with ESD224

10 Power Supply Recommendations

This device is a passive ESD device so there is no need to power it. Take care not to violate the recommended I/O specification (–3.6 V to 3.6 V) to ensure the device functions properly.

11 Layout

11.1 Layout Guidelines

- The optimum placement is as close to the connector as possible.
 - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
 - The PCB designer must minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- For the best ESD performance, do not use through-routing for the data channels. Connecting pins 1 and 10, 2 and 9, 4 and 7, 5 and 6 together with through routing will reduce the clamping voltage performance of ESD224.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
 - Electric fields tend to build up on corners, increasing EMI coupling.

11.2 Layout Examples

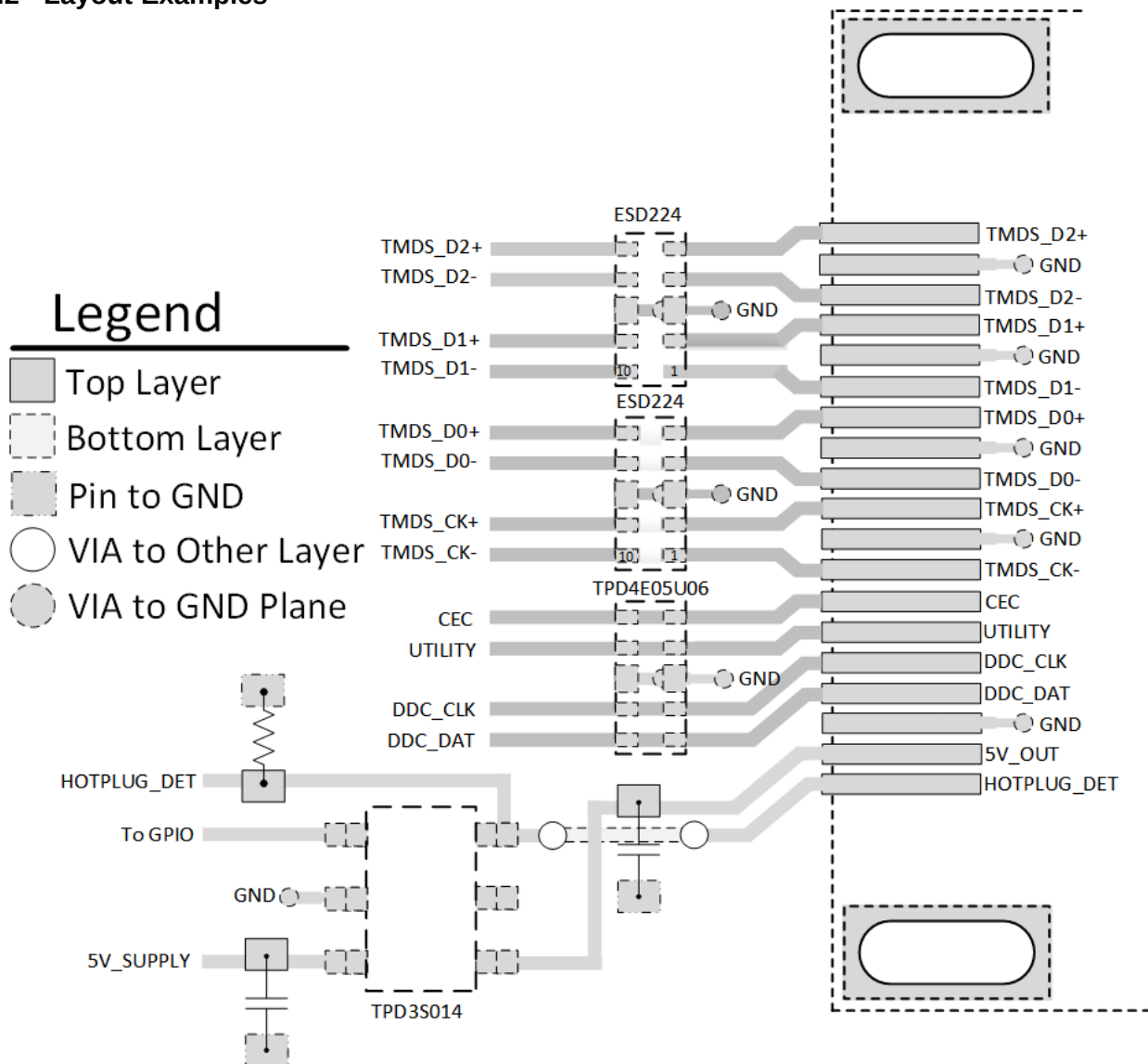


图 15. HDMI Type-A Transmitter Port Layout

注

There is no Through-Routing for the ESD224 Pins Connecting to the High Speed Data Lines.

12 デバイスおよびドキュメントのサポート

12.1 ドキュメントのサポート

12.1.1 関連資料

関連資料については、以下を参照してください。

12.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.comのデバイス製品フォルダを開いてください。右上の隅にある「通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

12.3 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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設計サポート *TIの設計サポート* 役に立つE2Eフォーラムや、設計サポート・ツールをすばやく見つけることができます。技術サポート用の連絡先情報も参照できます。

12.4 商標

E2E is a trademark of Texas Instruments.

12.5 静電気放電に関する注意事項



すべての集積回路は、適切なESD保護方法を用いて、取扱いと保存を行うようにして下さい。

静電気放電はわずかな性能の低下から完全なデバイスの故障に至るまで、様々な損傷を与えます。高精度の集積回路は、損傷に対して敏感であり、極めてわずかなパラメータの変化により、デバイスに規定された仕様に適合しなくなる場合があります。

12.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
ESD224DQAR	Active	Production	USON (DQA) 10	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1AR
ESD224DQAR.B	Active	Production	USON (DQA) 10	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1AR

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
ESD224DQAR	USON	DQA	10	3000	180.0	8.4	1.2	2.7	0.63	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ESD224DQAR	USON	DQA	10	3000	210.0	185.0	35.0

GENERIC PACKAGE VIEW

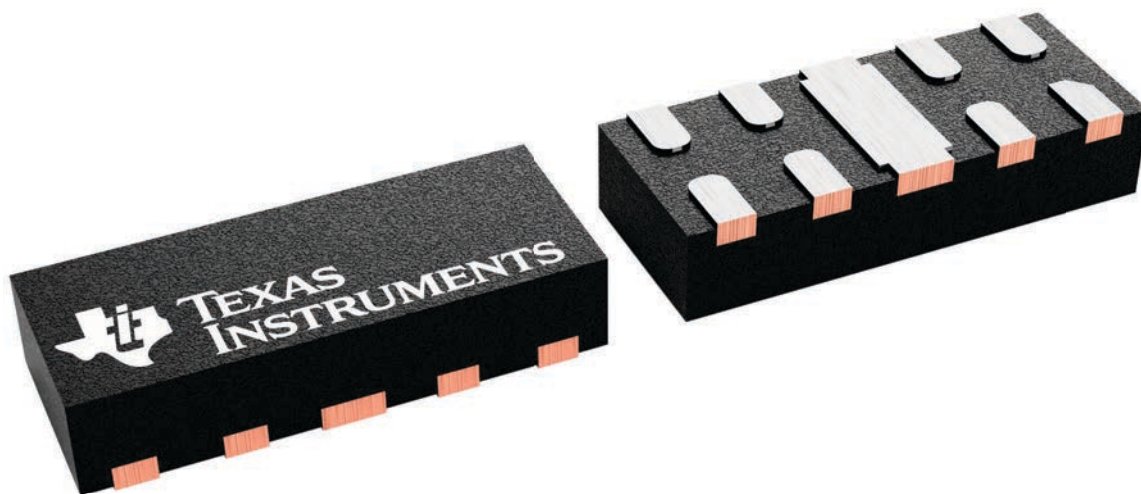
DQA 10

USON - 0.55 mm max height

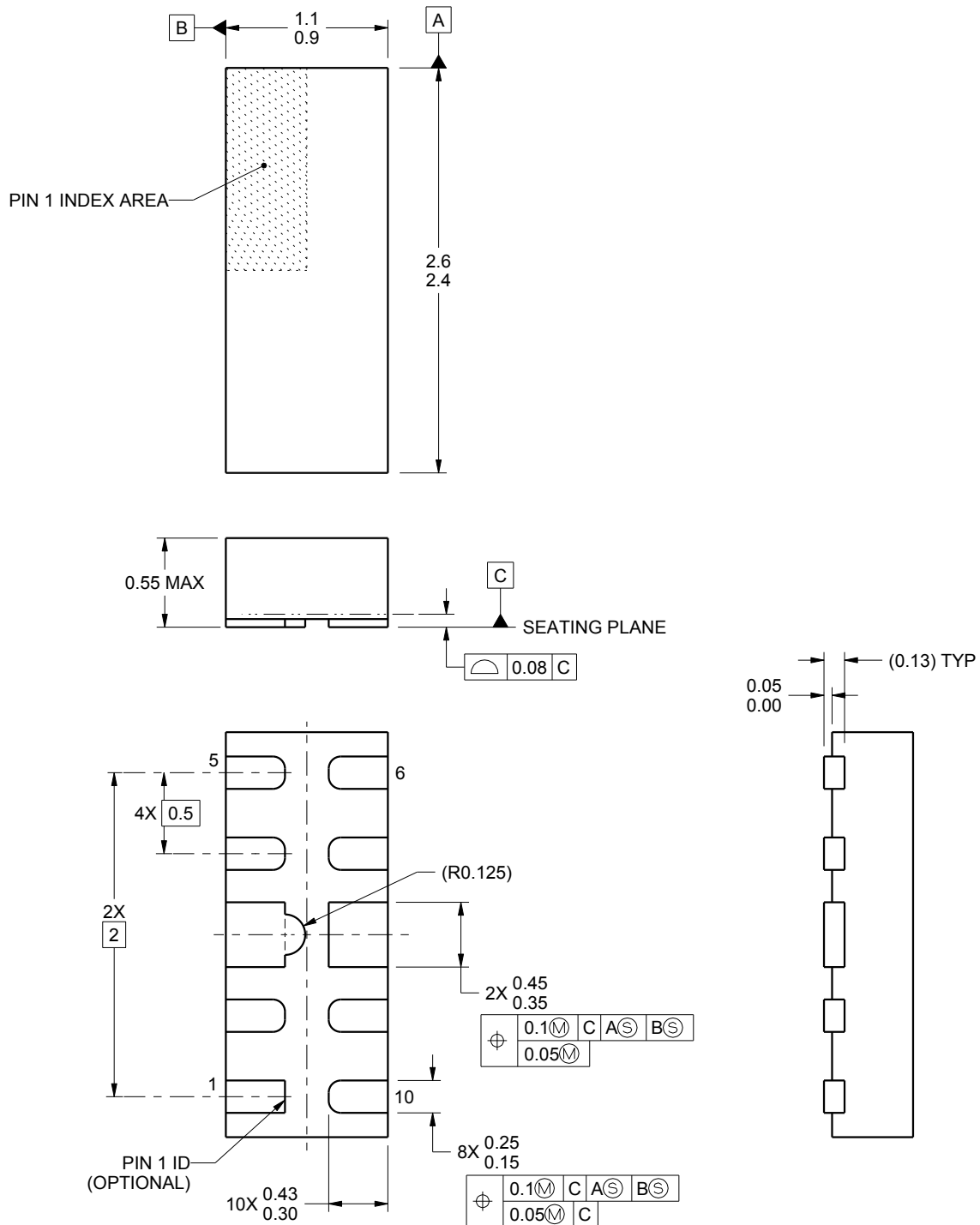
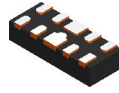
1 x 2.5, 0.5 mm pitch

PLASTIC SMALL OUTLINE - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4230320/A



4220328/A 12/2015

NOTES:

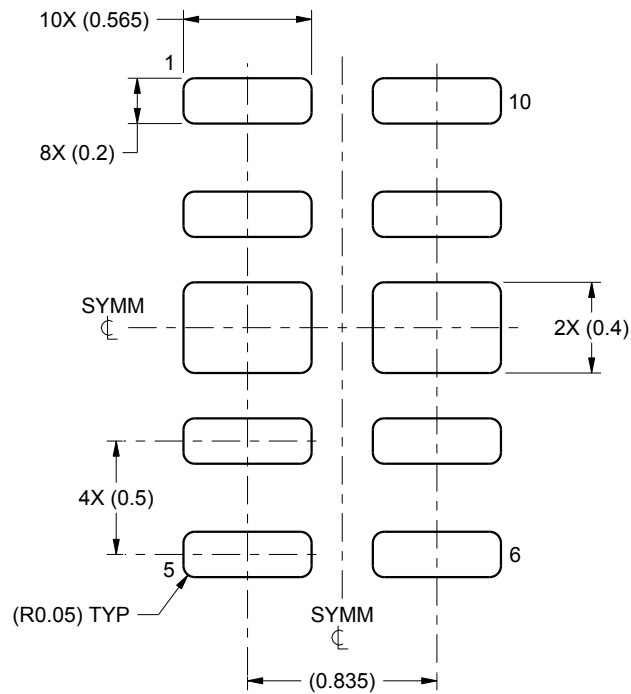
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

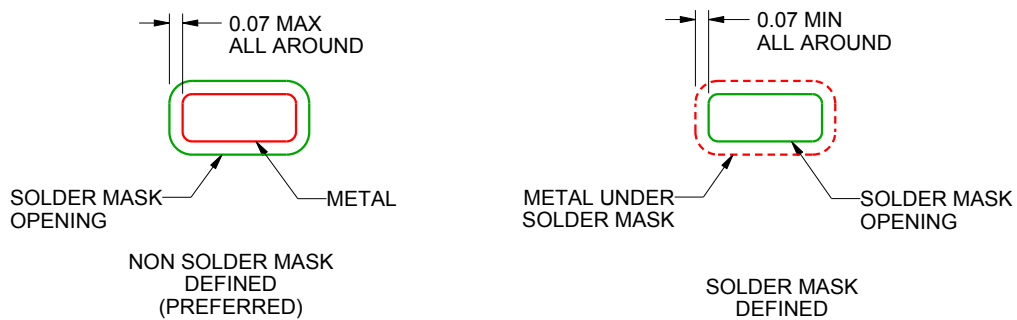
DQA0010A

USON - 0.55 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
SCALE:30X



SOLDER MASK DETAILS

4220328/A 12/2015

NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

DQA0010A

USON - 0.55 mm max height

Technical drawing of a 2x6 array of rectangular features on a plate. The drawing shows a top-down view with dimensions and symmetry indicators. The array is 10 units wide and 8 units high. The features are 10 units wide and 2 units high. The drawing includes dimensions for the overall size, individual feature size, and spacing. Symmetry is indicated by dashed lines and the word 'SYMM'. A note '(R0.05) TYP' points to the rounded corners of the features. A note 'METAL TYP' points to the material of the plate.

Dimensions:

- Overall width: 10X (0.565)
- Overall height: 8X (0.2)
- Feature width: 10
- Feature height: 2X (0.36)
- Spacing between features: 4X (0.5)
- Spacing between rows: 5
- Radius of corner: (R0.05) TYP
- Material: METAL TYP
- Symmetry: SYMM (indicated by dashed lines and the word 'SYMM')
- Feature count: 6
- Feature spacing: (0.835)

EXPOSED PADS 3 & 8:
90% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:40X

4220328/A 12/2015

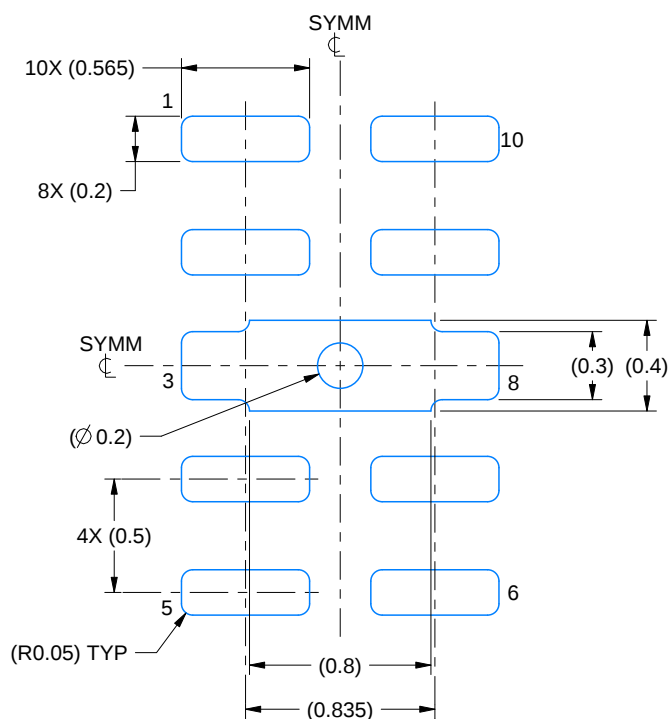
4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

EXAMPLE BOARD LAYOUT

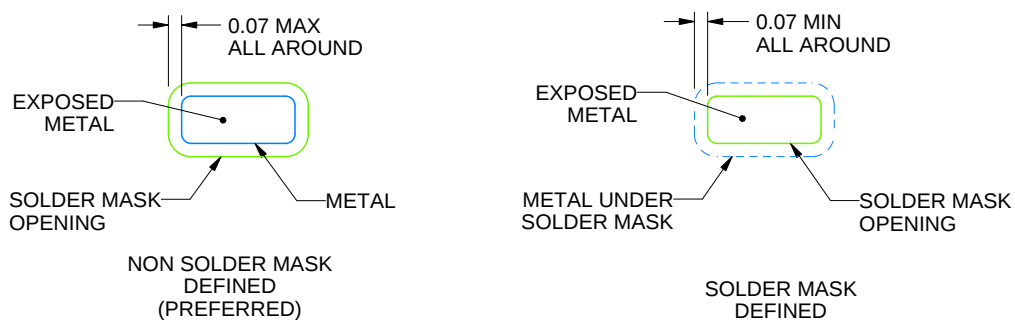
DQA0010B

USON - 0.55 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:30X



SOLDER MASK DETAILS

4230307/A 12/2023

NOTES: (continued)

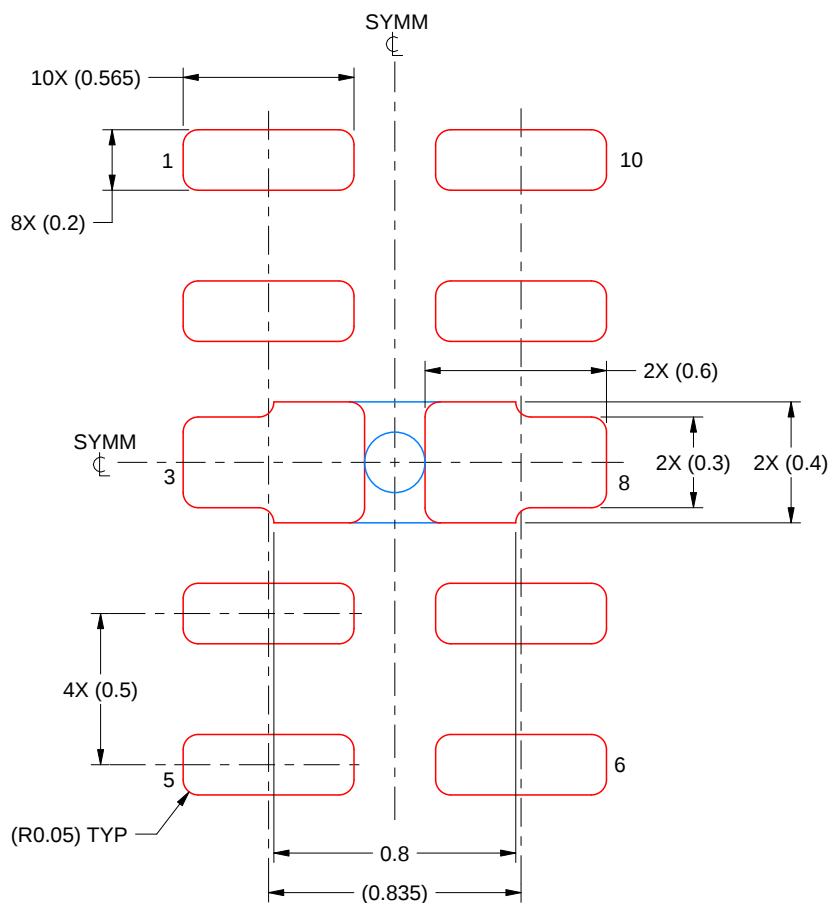
3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).

EXAMPLE STENCIL DESIGN

DQA0010B

USON - 0.55 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:40X

4230307/A 12/2023

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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